

BASIC BLADE & BEAM HEADER & SOCKET

(0.80 mm) .0315" PITCH • BTE/BSE SERIES



BTE
Mates:
BSE

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SPECIFICATIONS

Insulator Material:
Liquid Crystal Polymer
Contact Material:
Phosphor Bronze
Plating:
Au or Sn over 50 μ " (1.27 μ m) Ni
Operating Temp Range:
-55 °C to +125 °C
Current Rating:
2 A per pin
(2 pins powered)
Voltage Rating:
225 VAC/318 VDC
Max Cycles:
100

PROCESSING

Lead-Free Solderable:
Yes
SMT Lead Coplanarity:
(0.10 mm) .004" max (020-080)
(0.15 mm) .006" max (100-120)*
*(.004" stencil solution
may be available; contact
ipg@samtec.com)
Board Stacking:
For applications requiring more
than two connectors per board
or 80 positions or higher,
contact ipg@samtec.com

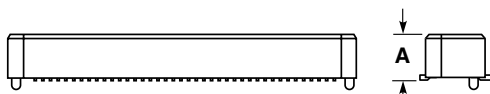
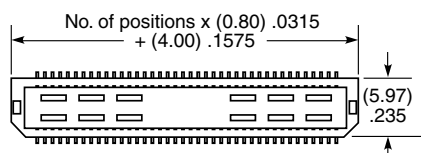
ALSO AVAILABLE Contact Samtec

30 μ " (0.76 μ m) Gold
Edge Mount Capability
Friction Lock option
11 mm, 14 mm, 16.10 mm,
19.10 mm, 22 mm, 25 mm
and 30 mm Stack
Height (Caution: Some
automatic placement/
inspection machines may
have component height
restrictions. Please consult
machinery specifications.)



Note:
Some lengths, styles and
options are non-standard,
non-returnable.

BTE	NO. OF POSITIONS PER ROW	LEAD STYLE	PLATING OPTION	D	A	OTHER OPTION
	-020, -040, -060, -080, -100, -120	Specify LEAD STYLE from chart	-F = Gold Flash on contact, Matte Tin on tail -L = 10 μ " (0.25 μ m) Gold on contact, Matte Tin on tail -C* = Electro-Polished Selective 50 μ " (1.27 μ m) min Au over 150 μ " (3.81 μ m) Ni on Signal Pins in contact area, Matte Tin over 50 μ " (1.27 μ m) min Ni on all solder tails (*-C Plating passes 10 year MFG testing)			-K = (7.00 mm) .275" DIA Polyimide Film Pick & Place Pad -TR = Tape & Reel (80 positions maximum) -FR = Full Reel Tape & Reel (must order maximum quantity per reel; contact Samtec for quantity breaks) (80 positions maximum)



LEAD STYLE	A
-01	(4.27) .168
-02	(7.21) .284

MATED HEIGHT

LEAD STYLE	MATED HEIGHT*
-01	(5.00 mm) .197"
-02	(8.00 mm) .315"

*Processing conditions
will affect mated height.

BSE	NO. OF POSITIONS PER ROW	01	PLATING OPTION	D	A	OTHER OPTION
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-020, -040, -060,
-080, -100, -120

-F
= Gold Flash on contact,
Matte Tin on tail

-L
= 10 μ " (0.25 μ m)
Gold on contact,
Matte Tin on tail

-C*
= Electro-Polished Selective
50 μ " (1.27 μ m) min
Au over 150 μ " (3.81 μ m)
Ni on Signal Pins in contact
area, Matte Tin over
50 μ " (1.27 μ m) min
Ni on all solder tails
(*-C Plating passes
10 year MFG testing)

-TR
= Tape & Reel
(80 positions
maximum)

-FR
= Full Reel
Tape & Reel
(must order
maximum
quantity per
reel; contact
Samtec for
quantity breaks)
(80 positions
maximum)

